

Ordering Information

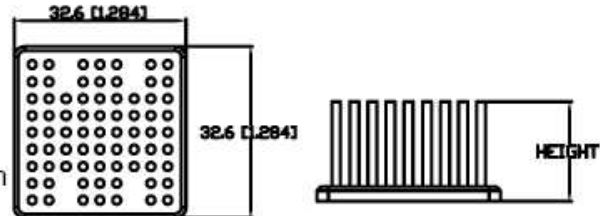
HH=Height		CC=Attachment
12mm	23mm	00 - None
15mm	28mm	01 - Yellow Clip
18mm	33mm	02 - Blue Clip
21mm		03 - Orange Clip
		05 - Special

BGA Heat Sink Specification

For 33x33 Chip set



- Material : CU1100
- Dimension :
Foot print : 33x33mm
Height : 12,15,18,21,23,28,33 mm
Base (thickness) : 2.6mm



- Finish: Antioxidant Treatment
- Chip set package thickness and clip color
3.3+/-0.25mm - Yellow clip
1.7+/-0.25mm - Blue clip
0.8+/-0.25mm - Orange clip
- Accessory :
Clip : Plastic (UL94-V0)
Thermal pad : T710 or others



Performance

Heat Source (LxW)	15x15
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